**FOR THE MEDIA**

ASMPT and KOKUSAI ELECTRIC Join Forces to Accelerate 2.5D and 3D Heterogeneous Integration Technology

Regensburg (Germany), **September 25, 2025 – ASMPT, the global leader in advanced packaging and assembly solutions, and KOKUSAI ELECTRIC CORPORATION, a pioneer in front-end semiconductor equipment, announced a Joint Development Agreement (JDA) to collaboratively advance hybrid bonding (HB) and micro-bump thermo-compression bonding (TCB) technologies. This strategic partnership is set to deliver more robust solutions to accelerate the adoption of 2.5D and 3D heterogeneous integration and empower the next wave of High-performance Computing (HPC) and Artificial Intelligence (AI) applications.**

This JDA combines KOKUSAI ELECTRIC’s sophisticated thin-film technology with ASMPT’s ultra-high-precision bonding technology to deliver more robust HB and micro-bump TCB solutions that will lead to more effective solutions for advanced 2.5D and 3D packaging, with improved product quality, yield, and accelerated time-to-market for high-performance, energy-efficient chips.

“By integrating our state-of-the-art thin-film technology with ASMPT’s precision bonding platforms, we are addressing critical advanced packaging process challenges and setting new industry benchmarks for both hybrid bonding and thermo-compression bonding,” explained Hidehiro Yanagawa, Executive VP of KOKUSAI ELECTRIC CORPORATION. “Our partnership with KOKUSAI ELECTRIC will truly push the boundaries of advanced packaging technology,” remarked Nelson Fan, VP of ASMPT SEMI Solutions’ AP Business Group. “Through this close collaboration, we are looking forward to unlocking further possibilities with our patented *AOR TCB™* (the process with our FIREBIRD bonder), and our cutting-edge LITHOBOLT® hybrid bonding platform, to deliver robust, scalable, and high-quality solutions for the future.”

This alliance positions both companies as leaders in semiconductor packaging innovation for next-generation computing technologies.

**Illustrations for downloading**

The following images are available for download in printable format at:   
<https://kk.htcm.de/press-releases/asmpt/>

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| スーツを着た男性  AI 生成コンテンツは誤りを含む可能性があります。 |  |  |
| **Hidehiro Yanagawa, Executive Director, Executive VP and Executive Officer, KOKUSAI ELECTRIC CORPORATION**  Image credit: KOKUSAI ELECTRIC CORPORATION | **Nelson Fan, VP of Advanced Packaging Business Group, ASMPT SEMI Solutions**  Image credit: ASMPT | **LITHOBOLT®, Hybrid Bonding Platform - Next evolution of IC**  **interconnect solutions for**  **heterogeneous integration**  Image credit: ASMPT |

About ASMPT Limited (“ASMPT”)

ASMPT Limited is a leading global supplier of hardware and software solutions for the manufacture of semiconductors and electronics. Headquartered in Singapore, ASMPT’s offerings encompass the semiconductor assembly & packaging, and SMT (surface mount technology) industries, ranging from wafer deposition to the various solutions that organise, assemble, and package delicate electronic components into a vast range of end-user devices, which include electronics, mobile communications, computing, automotive, industrial and LED (displays). ASMPT partners with customers very closely, with continuous investment in R&D helping to provide cost-effective, industry-shaping solutions that achieve higher productivity, greater reliability, and enhanced quality. ASMPT is also a founding member of the [Semiconductor Climate Consortium](https://www.linkedin.com/showcase/semiconductor-climate-consortium/about/).

ASMPT is listed on the Stock Exchange of Hong Kong (HKEX stock code: 0522), and is one of the constituent stocks of the Hang Seng Composite MidCap Index under the Hang Seng Composite Size Indexes, the Hang Seng Composite Information Technology Industry Index under the Hang Seng Composite Industry Indexes, the Hang Seng Corporate Sustainability Benchmark Index, and the Hang Seng HK 35 Index.

To learn more about ASMPT, please visit us at asmpt.com.

About ASMPT Semiconductor Solutions (“ASMPT SEMI”)

ASMPT SEMI is the leading provider of forward-looking solutions for advanced packaging and semiconductor assembly. With its commitment to innovation and customer satisfaction, ASMPT SEMI offers a comprehensive range of products and services that meet the evolving needs of the microelectronics industry. Expert knowledge covers areas such as flip-chip and wafer-level packaging, advanced interconnect technologies, and more. ASMPT SEMI’s state-of-the-art solutions enable customers to achieve higher performance, greater reliability, and improved cost-efficiency in the manufacturing of their semiconductor devices.

ASMPT SEMI sees itself as a pioneer and driving force of the Intelligence Revolution. With its advanced packaging and assembly technologies, the business segment creates the invisible connections that enable intelligent applications in Artificial Intelligence, Smart Mobility, and Hyperconnectivity.

For more information about ASMPT SEMI, visit semi.asmpt.com.

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